

SOT380-1

plastic leaded chip carrier; 20 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC20
Package type industry code	PLCC20
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	112E04
JEDEC package outline code	MS-018
JEITA package outline code	EDR-7319
Mounting method type	S (surface mount)
Issue date	20-11-2001

Table 1. Package summary

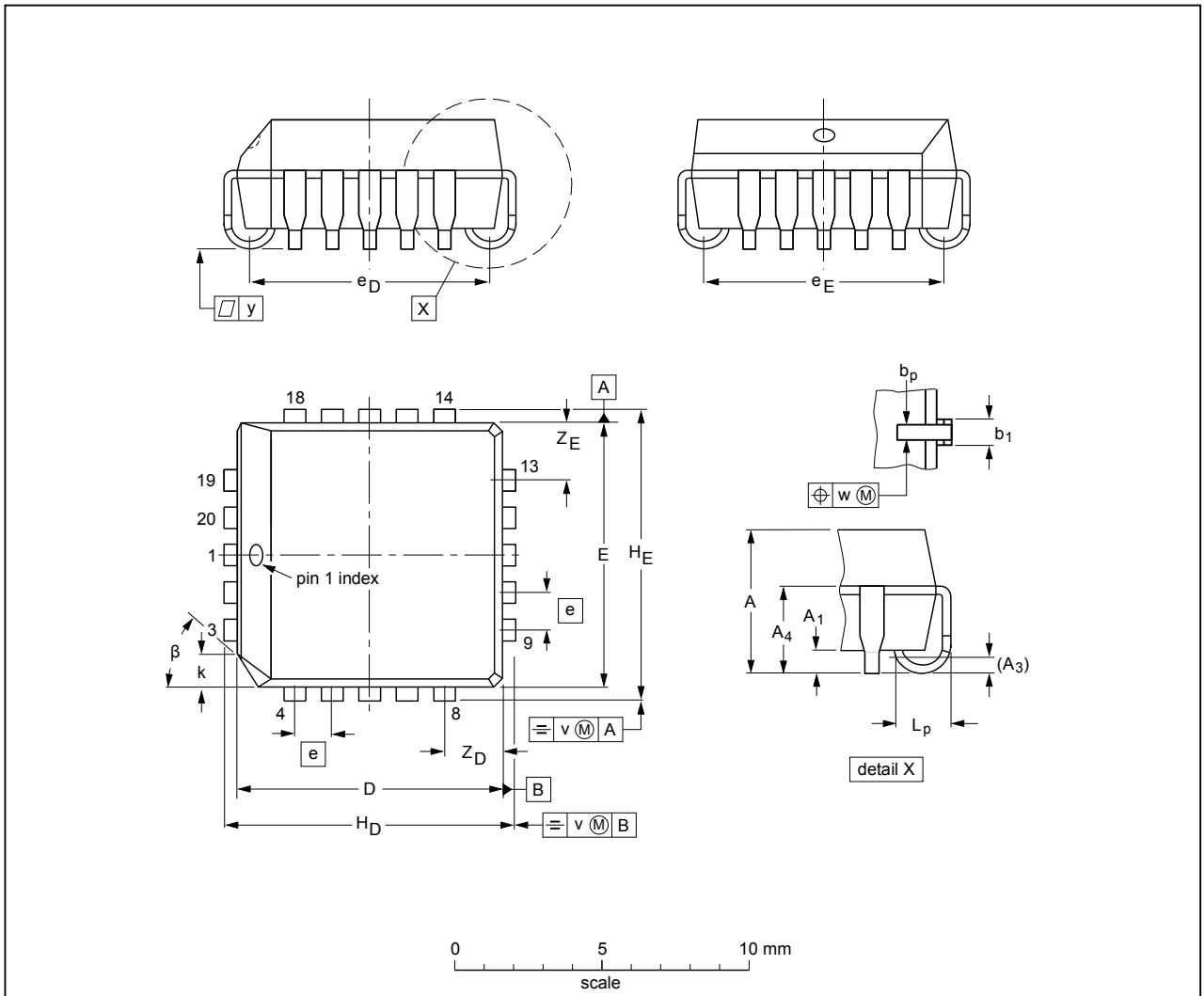
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.89	-	8.91	9.04	mm
E	package width	8.89	-	8.91	9.04	mm
A	seated height	4.19	-	4.57	4.57	mm
A ₂	package height	[tbd]	-	3.81	[tbd]	mm
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

PLCC20: plastic leaded chip carrier; 20 leads

SOT380-1



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A ₁ min.	A ₃	A ₄ max.	b _p	b ₁	D ⁽¹⁾	E ⁽¹⁾	e	e _D	e _E	H _D	H _E	k	L _p	v	w	y	Z _D ⁽¹⁾ max.	Z _E ⁽¹⁾ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	9.04 8.89	9.04 8.89	1.27	8.38 7.37	8.38 7.37	10.03 9.78	10.03 9.78	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.356 0.350	0.356 0.350	0.05	0.33 0.29	0.33 0.29	0.395 0.385	0.395 0.385	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT380-1	112E04	MS-018	EDR-7319		01-10-24 01-11-20

Fig. 1. Package outline PLCC20 (SOT380-1)

3. Soldering

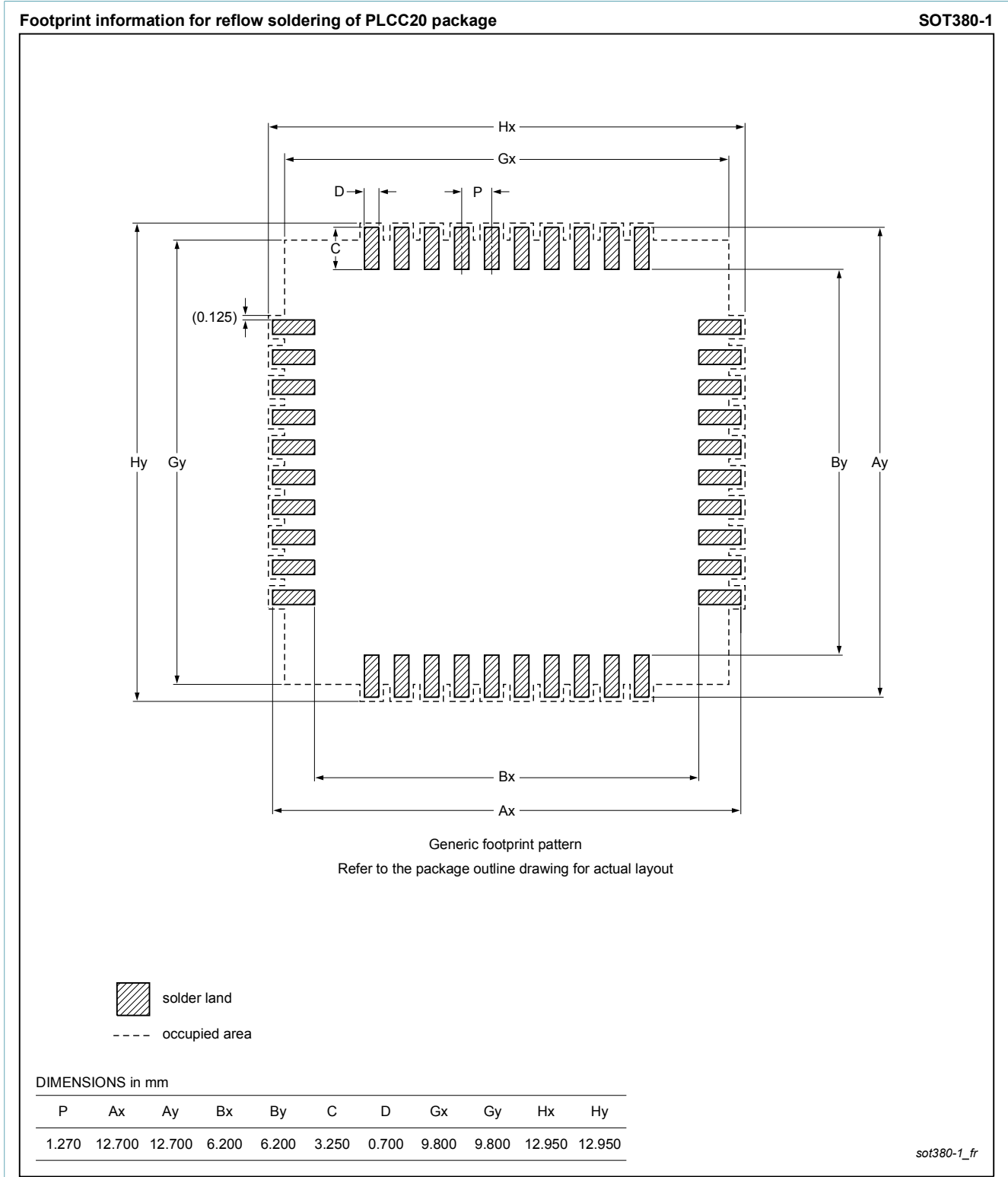


Fig. 2. Reflow soldering footprint for PLCC20 (SOT380-1)

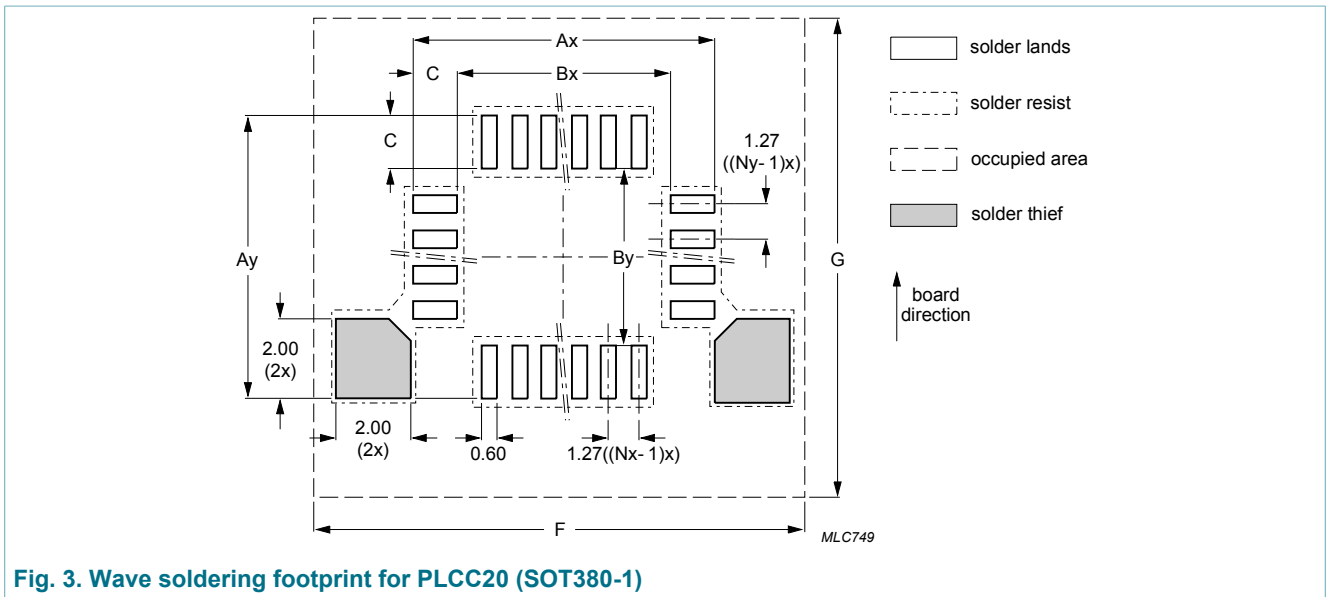


Fig. 3. Wave soldering footprint for PLCC20 (SOT380-1)

4. Legal information

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